



RoHS Compliant

**MAX
260°C**

**MSL
1**



PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit 242.10	ppm
768 14								
Alumina Ceramic	Al2O3	1344-28-1	0.8750	0.2118	87.50%	185.3578	76.56%	765625
	SiO2 (silicon dioxide)	14808-60-7			12.50%	26.4797	10.94%	109375
Conductor Thick Film	Ag	7440-22-4	0.0059	0.0014	100.00%	211.8375		
	Pd	7440-05-3			99.00%	1.4141	0.58%	5841
Resistor Thick Film					1.00%	0.0143	0.01%	59
					100.00%	1.4284		
	RuO2	12036-10-1	0.0074	0.0018	30.00%	0.5375	0.22%	2220
	PbO	1317-36-8			10.00%	0.1792	0.07%	740
Notch Conductor Thick Film	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.5375	0.22%	2220
	B2O3	1303-86-2			30.00%	0.5375	0.22%	2220
					100.00%	1.7915		
Lead Wire	Ag	7440-22-4	0.0112	0.0027	72.02%	1.9528	0.81%	8066
	Pd	7440-05-3			4.20%	0.1139	0.05%	470
	Pt	7440-06-4			23.78%	0.6448	0.27%	2663
					100.00%	2.7115		
Lead Under-Plating	Cu	7440-50-8	0.0360	0.0087	100.00%	8.7156	3.60%	36000
Solder					100.00%	8.7156		
	Ni	7440-02-0	0.0100	0.0024	100.00%	2.4210	1.00%	10000
Covercoat					100.00%	2.4210		
	Ag	7440-22-4	0.0360	0.0087	3.00%	0.2615	0.11%	1080
	Cu	7440-50-8			0.50%	0.0436	0.02%	180
	Sn	7440-31-5			96.50%	8.4106	3.47%	34740
					100.00%	8.7156		
Covercoat	TiO2	13463-67-7	0.0185	0.0045	50.00%	2.2394	0.93%	9250
	Phenolic Resin	55185-45-0			25.00%	1.1197	0.46%	4625
	Epoxy Resin	25068-38-6			25.00%	1.1197	0.46%	4625
		Sum	1.0000	0.2421	100.00%	4.4789		
			part weight	0.2421				
		Totals:		0.2421		242.10	100.00%	1000000

RoHS exemption claimed for lead in glass of electronic component